

SURFACE MOUNT UES RECTIFIERS

POWERMITE™ Package
High Efficiency, 2A, 50nSec

UPR20
UPR30
UPR40

FEATURES

- High Power Surface Mount Package
- Ultra-fast Recovery Time (50nS)
- Low Forward Voltage
- Integral Heat Sink/Locking Tabs
- Compatible with Automatic Insertion Equipment
- Full Metallic Bottom Eliminates Flux Entrapment

DESCRIPTION

In Microsemi's new Powermite SMT package, these high efficiency ultrafast rectifiers offer the power handling capabilities previously found only in much larger packages. They are ideal for SMD applications that operate at high frequencies.

In addition to its size advantages, Powermite package features include a full metallic bottom that eliminates the possibility of solder flux entrapment during assembly, and a unique locking tab acts as an integral heat sink. Its innovative design makes this device ideal for use with automatic insertion equipment.

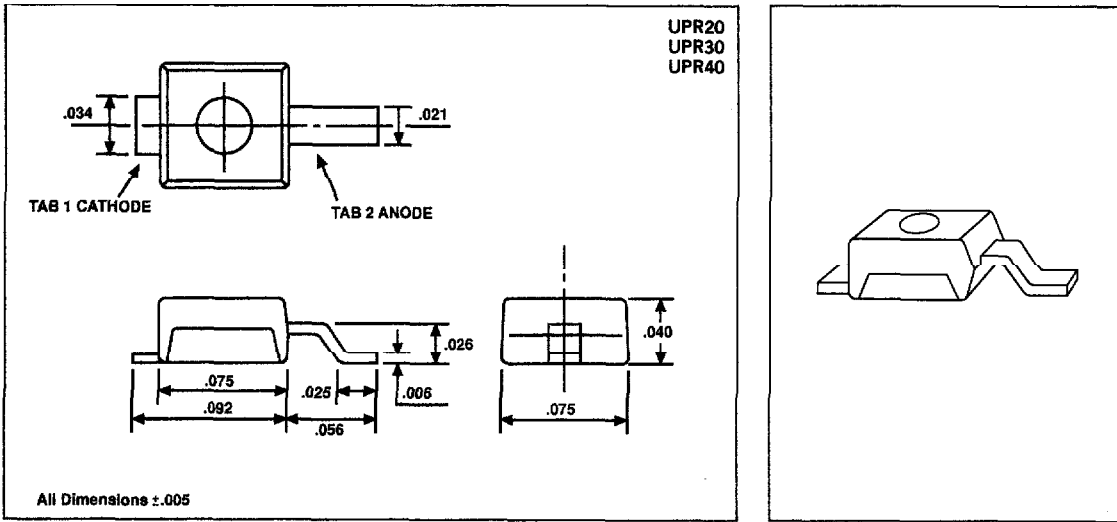
ABSOLUTE MAXIMUM RATINGS

Maximum Reverse Voltage, UPR20	200V
Maximum Reverse Voltage, UPR30	300V
Maximum Reverse Voltage, UPR40	400V
Maximum Average Output Current, $T_{TAB 1} = 75^{\circ}\text{C}$	2.0A*
Thermal Resistance, Junction to Tab	30°C/W
Thermal Resistance, Junction to Bottom	10°C/W
Non-Repetitive Sinusoidal Surge Current (8.3ms)	20A
Operating and Storage Temperature	-55°C to +150°C

*WHEN MOUNTED ON A PC BOARD WITH 2 OZ. COPPER.

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MECHANICAL SPECIFICATIONS



ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$ unless noted)

TEST	CONDITIONS	LIMIT	UNITS
Forward Voltage, V_F	$I_F = 1 \text{ Amp}$	1.25	Volts
Forward Voltage, V_F	$I_F = 1 \text{ Amp}, T_J = 100^\circ\text{C}$	1.15	Volts
Reverse Current, I_R	$V_R = \text{Max Rating}$	10	μAmps
Reverse Current, I_R	$V_R = \text{Max Rating}, T_J = 100^\circ\text{C}$	100	μAmps
Reverse Recovery Time, T_{RR}	$I_F = 0.5\text{A}, I_R = 1.0\text{A}$ $I_{REC} = 0.25 \text{ A}$	50	nSec

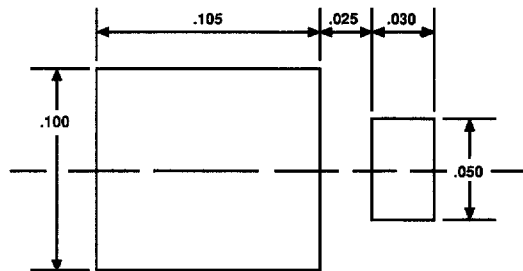


Figure 1. Suggested Mounting Pad Dimensions